

AMENDMENTS TO THE SPECIFICATION

Please amend paragraph [0054] as follows:

[0054] It is anticipated that a ~~second~~ first layer 12''' and a third layer 16''' can be formed similarly to that of any of the layers described above. The next step of the method of forming the micromachined device 10''' includes positioning the second layer 14''' between the first layer 12''' and third layer 16'''. Thus, the movable portion 66 of the second layer 14''' will be restrained between the first layer 12''' and the third layer 16'''. Once the layers are positioned in this overlapping manner, a layer bonding process, such as one of those described above, can be used to bond the layers 12'', 14'', 16'' together. It is preferred that the bonding process is a silicon bonding process, although any suitable bonding process can be used. Due to the presence of the coating material 62, the movable portion 66 of the second layer 14''' will not bond with the first layer 12''' or third layer 16'''.